

**United States Patent [19]**

Nakashiba et al.

**[11] Patent Number:** 5,762,539**[45] Date of Patent:** Jun. 9, 1998**[54] APPARATUS FOR AND METHOD FOR POLISHING WORKPIECE**

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**[51] Int. Cl.<sup>6</sup>** B24B 5/00

**[52] U.S. Cl.** 451/41; 451/5; 451/285; 451/286; 451/287; 451/288; 451/289; 451/388

**[58] Field of Search** 451/41, 285-289, 451/388, 53, 5

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**[57] ABSTRACT**

A polishing apparatus for polishing a workpiece such as a semiconductor wafer has a turntable with a polishing surface, and a top ring for holding a workpiece and pressing the workpiece against the polishing surface under a first pressing. The polishing apparatus has a pressurized fluid source for supplying pressurized fluid, and a plurality of openings provided in the holding surface of the top ring for ejecting the pressurized fluid supplied from the pressurized fluid source. A plurality of areas each having the openings are defined on the holding surface so that the pressurized fluid is selectively ejectable from the openings in the respective areas.

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11 Claims, 9 Drawing Sheets

